



3K1480 thermal conductive silicon pad

3K1480 thermal conductive silicon pad is high-performance thermal conductive gap filling materials, mainly for the transmission interface between the electronic equipment and heat sink or product outer coving. Nice stickiness, flexibility, good compression performance and excellent heat conductivity are designed for 3K1480series, which make the products can discharge gas from the electronic original and heat sink, to achieve fully conforming and obviously cooling effect. Compared to common thermal conductive & insulating materials, 3k1480 series has certain stickiness which bring great convenience in the product installation processing, not easy to fall off and easy to operate.



Features & benefits:

- High reliability & High thermal conductivity
- High compressibility, soft and flexible
- Natural stickiness, no extra surface frontal adhesives
- Meet with the environmental requirements of ROHS and UL

Typical applications:

- Communication equipment
- LED Light
- Switching power supply
- Back light model
- Medical equipment
- Mobile equipment
- Video equipment
- Networking equipment
- Household appliances
- PC server/workstations

Application modes:

- The filling between PCB and heat sink
- The filling between IC and heat sink or product outer coving
- The filling between IC and similar heatsink cooling materials

| Test item | Test method | Unit | 3K1480Test Value |
|---------------------|-------------|--------------------|----------------------|
| Color | Visual | | Grey/blue/white |
| Thickness | ASTM D374 | Mm | 0.5 to 20 |
| Specific Gravity | ASTM D792 | g/cm ³ | 3.1±0.1 |
| Hardness | ASTM D2240 | Shore C | 20±5 to 60±5 |
| Tensile Strength | ASTM D412 | kg/cm ² | 50 |
| | ASTM D412 | Pa | 5.9*10 ⁹ |
| Continuous Use Temp | EN344 | ℃ | -40 to +220 |
| Volume Resistivity | ASTM D257 | Ω-CM | 2.9*10 ¹¹ |
| Breakdown Voltage | ASTM D149 | KV/mm | 10 |
| Flame Rating | UL-94 | | V-0 |
| Conductivity | ASTM D5470 | w/m-k | 14.8 |